

Features

- Advanced trench technology
- Fast switching speed
- Green device available
- RoHS compliant with Halogen-free

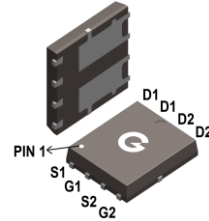
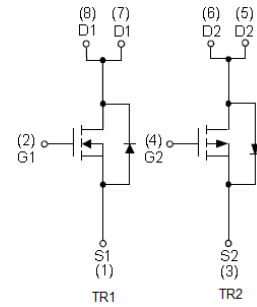
HF

Applications

- Synchronous Rectification
- Motor Control
- Portable equipment application

Mechanical Data

- Case: PDFN5x6-8LC
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



PDFN5x6-8LC

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
GBLHAA02-5DL8	PDFN5x6-8LC	5000 pcs / Tape & Reel	GBLHAA02

Maximum Ratings (@ T_C = 25°C unless otherwise specified)

Parameter	Symbol	N Channel	P Channel	Unit
Drain-to-Source Voltage	V _{DSS}	100	-100	V
Gate-to-Source Voltage	V _{GSS}	±20	±20	V
Continuous Drain Current (T _C = 25°C)	I _D	10	-6	A
Continuous Drain Current (T _C = 100°C)		6.3	-3.8	A
Continuous Drain Current (T _A = 25°C) ^{*1}		2.5	-1.6	A
Continuous Drain Current (T _A = 100°C) ^{*1}		1.6	-1	A
Pulsed Drain Current (t _p = 10μs, T _C = 25°C)	I _{DM}	40	-24	A
Single Pulse Avalanche Energy ^{*3}	E _{AS}	14	14	mJ
Power Dissipation (T _C = 25°C)	P _D	25	25	W
Operating Junction Temperature Range	T _J	-55 ~ +150		°C
Storage Temperature Range	T _{STG}	-55 ~ +150		°C

Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	-	-	5	$^{\circ}C/W$
Thermal Resistance Junction-to-Air ^{*1}	$R_{\theta JA}$	-	-	70	$^{\circ}C/W$

Electrical Characteristics-N (@ $T_A = 25^{\circ}C$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
V_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	100	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 100V, V_{GS} = 0V$	-	-	1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	± 100	nA
On Characteristics						
$R_{DS(ON)}$	Drain-Source On-resistance ^{*2}	$V_{GS} = 10V, I_D = 5A$	-	80	120	m Ω
		$V_{GS} = 4.5V, I_D = 3A$	-	84	140	m Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.5	2.5	V
R_G	Gate Resistance	$V_{GS} = 0V, f = 1MHz$	-	3.5	-	Ω
Dynamic Characteristics						
C_{ISS}	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1.0MHz$	-	1010	-	pF
C_{OSS}	Output Capacitance		-	36	-	
C_{RSS}	Reverse Transfer Capacitance		-	31	-	
Switching Characteristics						
$t_{d(ON)}$	Turn-on Delay Time ^{*4}	$V_{DD} = 50V$ $I_D = 5A$ $R_G = 5\Omega$	-	9	-	ns
t_r	Turn-on Rise Time ^{*4}		-	13	-	
$t_{d(OFF)}$	Turn-Off Delay Time ^{*4}		-	22	-	
t_f	Turn-Off Fall Time ^{*4}		-	7.5	-	
Q_G	Total Gate-Charge	$V_{DD} = 50V$ $V_{GS} = 10V$ $I_D = 5A$	-	24.5	-	nC
Q_{GS}	Gate to Source Charge		-	2.4	-	
Q_{GD}	Gate to Drain (Miller) Charge		-	5.5	-	
Source-Drain Diode Characteristics						
V_{SD}	Diode Forward Voltage ^{*2}	$I_{SD} = 5A, V_{GS} = 0V$	-	0.84	1.2	V
t_{rr}	Reverse Recovery Time	$I_S = 5A, V_{GS} = 0V$ $di/dt = 100A/\mu s$	-	34	-	ns
Q_{rr}	Reverse Recovery Charge		-	39	-	nC

Electrical Characteristics-P (@ T_A = 25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
V _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = -250μA	-100	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -100V, V _{GS} = 0V	-	-	-1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} = ±20V, V _{DS} = 0V	-	-	±100	nA
On Characteristics						
R _{DS(ON)}	Drain-Source On-resistance *2	V _{GS} = -10V, I _D = -3A	-	280	310	mΩ
		V _{GS} = -4.5V, I _D = -3A	-	295	340	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250μA	-1	-1.8	-2.5	V
R _G	Gate Resistance	V _{GS} = 0V, f = 1MHz	-	7	-	Ω
Dynamic Characteristics						
C _{ISS}	Input Capacitance	V _{GS} = 0V V _{DS} = -25V f = 1.0MHz	-	1192	-	pF
C _{OSS}	Output Capacitance		-	33	-	
C _{RSS}	Reverse Transfer Capacitance		-	28	-	
Switching Characteristics						
t _{d(ON)}	Turn-on Delay Time *4	V _{DD} = -50V I _D = -3A R _G = 5Ω	-	8	-	ns
t _r	Turn-on Rise Time *4		-	16	-	
t _{d(OFF)}	Turn-Off Delay Time *4		-	36	-	
t _f	Turn-Off Fall Time *4		-	18	-	
Q _G	Total Gate-Charge	V _{DD} = -50V	-	26.5	-	nC
Q _{GS}	Gate to Source Charge	V _{GS} = -10V	-	3.5	-	
Q _{GD}	Gate to Drain (Miller) Charge	I _D = -5A	-	4.2	-	
Source-Drain Diode Characteristics						
V _{SD}	Diode Forward Voltage *2	I _{SD} = -3A, V _{GS} = 0V	-	-0.9	-1.2	V
t _{rr}	Reverse Recovery Time	I _S = -5A, V _{GS} = 0V di/dt = 100A/μs	-	50	-	ns
Q _{rr}	Reverse Recovery Charge		-	93	-	nC

Notes:

- The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper
- The data tested by pulsed, pulse width ≤ 300μs, duty cycle ≤ 2%
- The E_{AS} data shows Max. rating. The test condition is: N channel: V_{DD} = 50V, V_{GS} = 10V, L = 0.5mH
P channel: V_{DD} = -50V, V_{GS} = -10V, L = 0.5mH
- Guaranteed by design, not subject to production

Ratings and Characteristics Curves-N (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

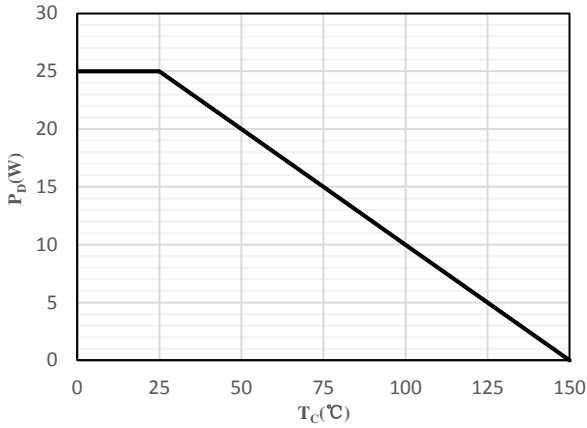


Fig 1 Power Dissipation

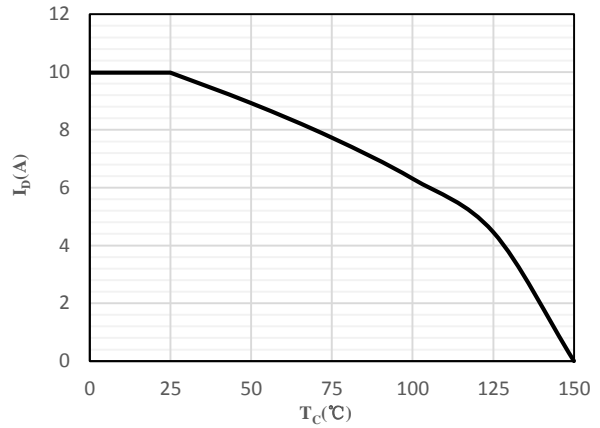


Fig 2 Drain Current

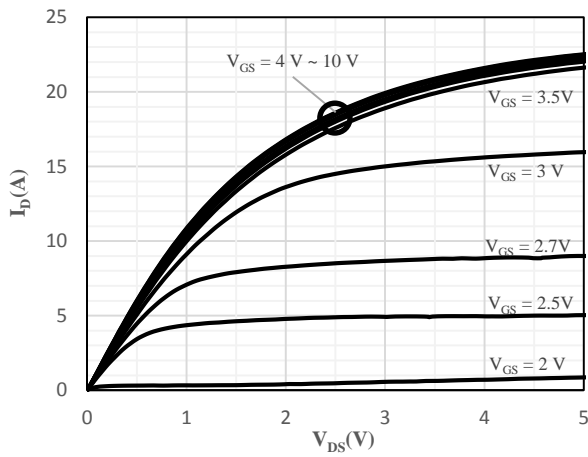


Fig 3 Typical Output Characteristics

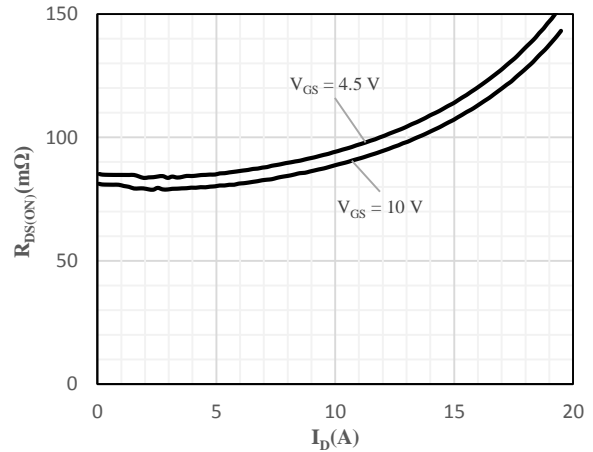


Fig 4 On-Resistance vs. Drain Current and Gate Voltage

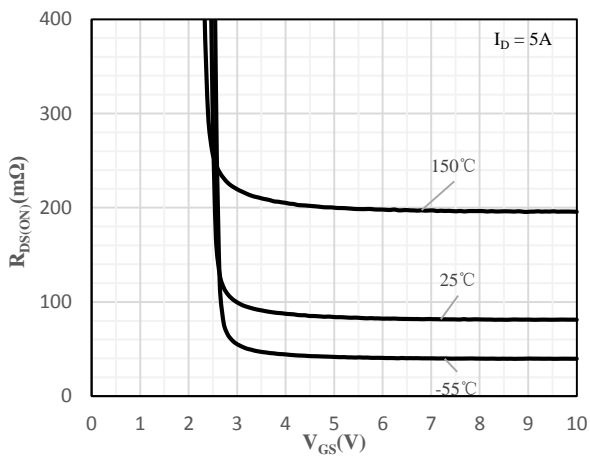


Fig 5 On-Resistance vs. Gate-Source Voltage

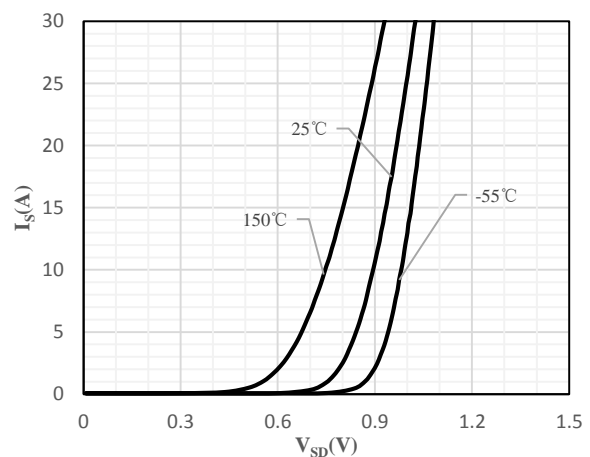


Fig 6 Body-Diode Characteristics

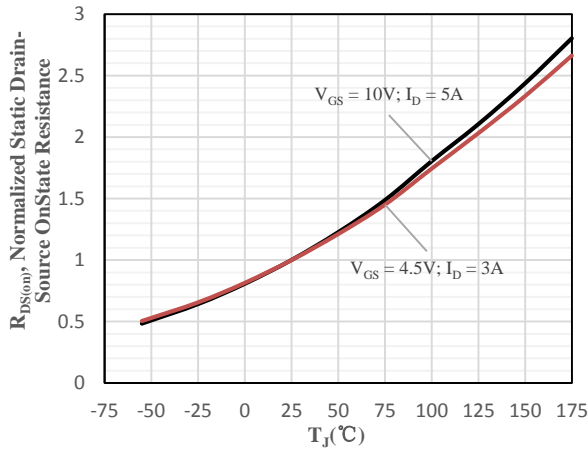


Fig 7 Normalized On-Resistance vs. Junction Temperature

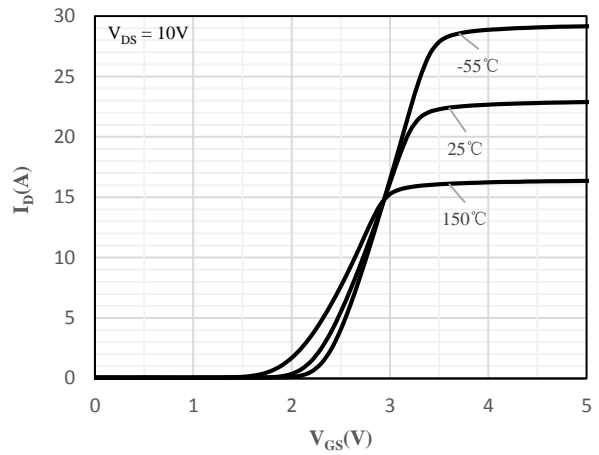


Fig 8 Transfer Characteristics

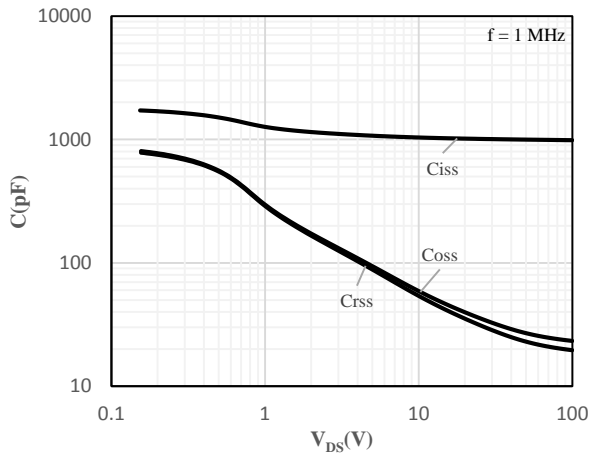


Fig 9 Capacitance Characteristics

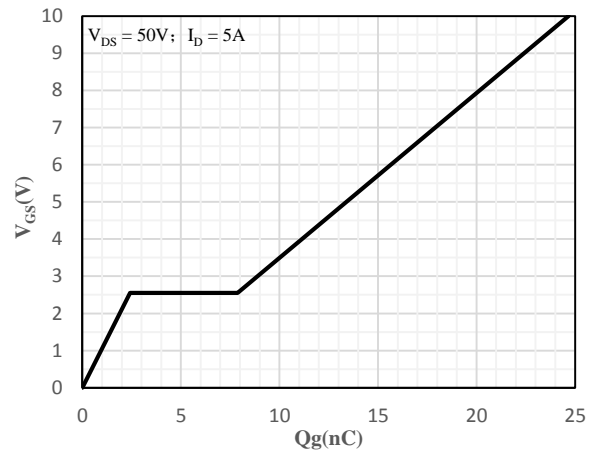


Fig 10 Gate-Charge Characteristics

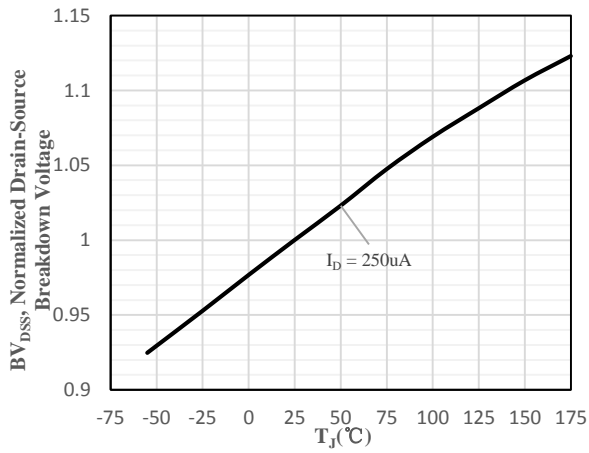


Fig 11 Normalized Breakdown Voltage vs. Junction Temperature

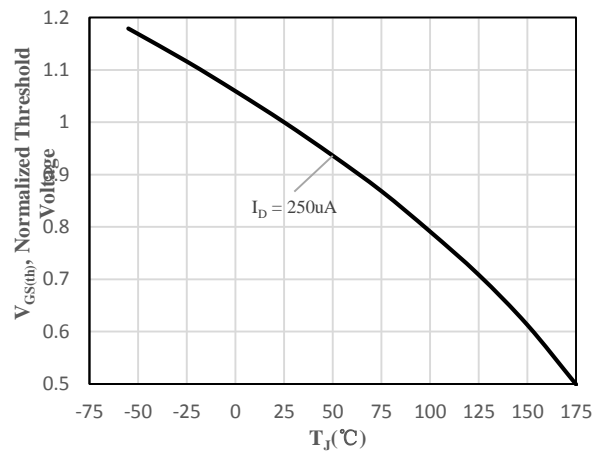


Fig 12 Normalized $V_{GS(th)}$ vs. Junction Temperature

Ratings and Characteristics Curves-P (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

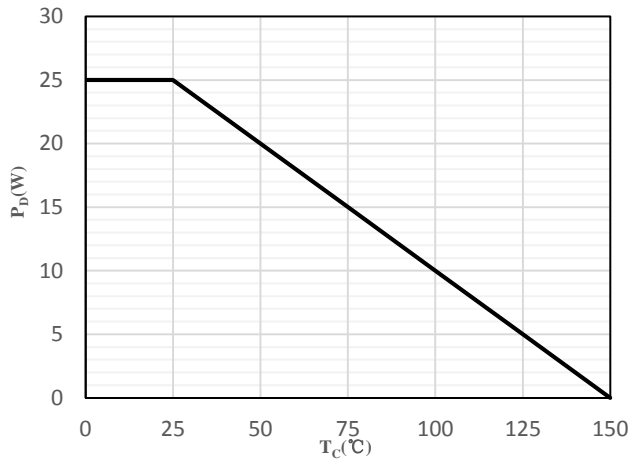


Fig 1 Power Dissipation

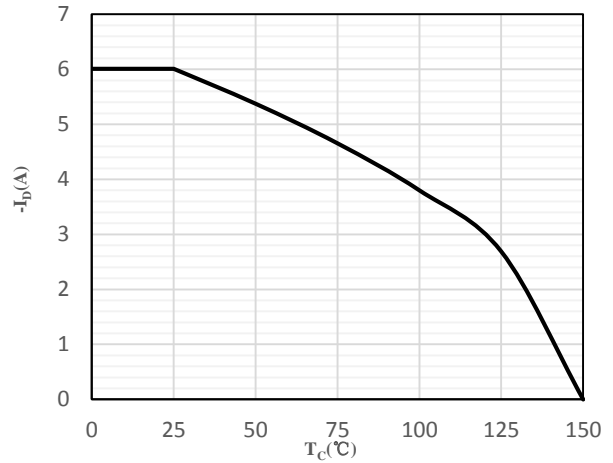


Fig 2 Drain Current

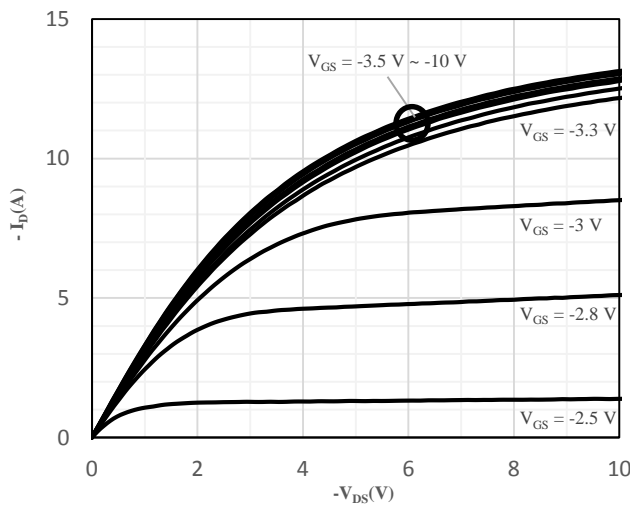


Fig 3 Typical Output Characteristics

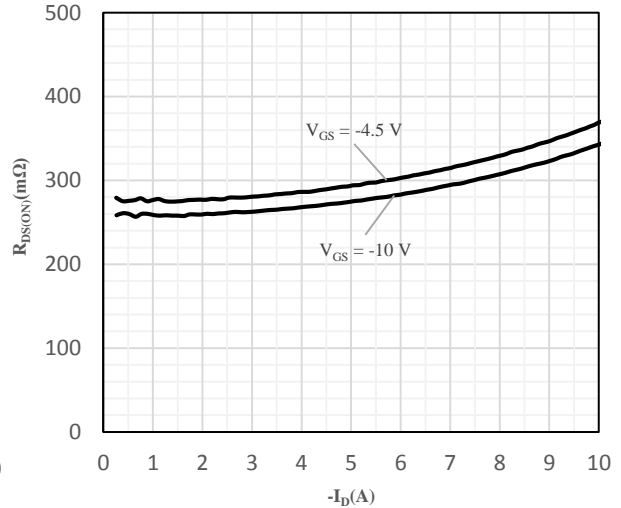


Fig 4 On-Resistance vs. Drain Current and Gate Voltage

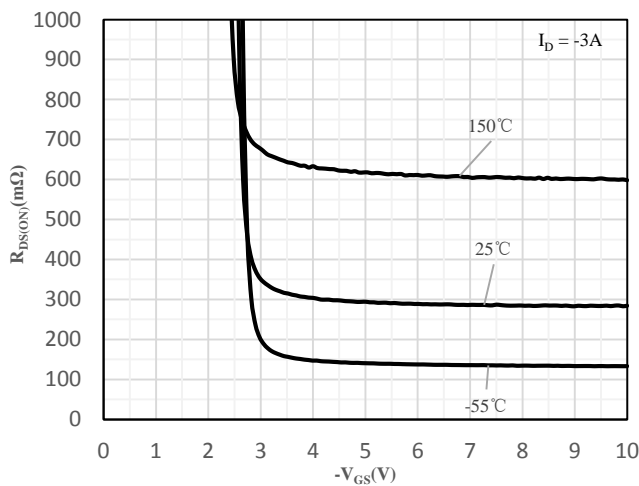


Fig 5 On-Resistance vs. Gate-Source Voltage

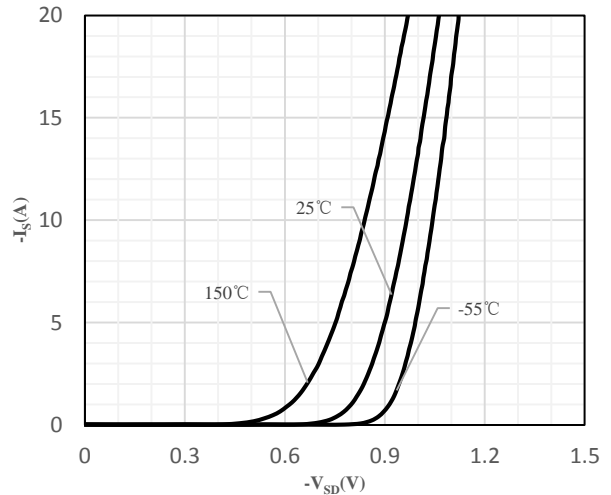


Fig 6 Body-Diode Characteristics

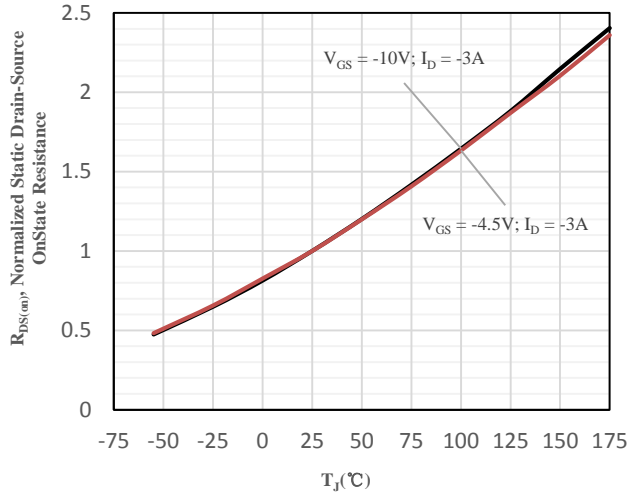


Fig 7 Normalized On-Resistance vs. Junction Temperature

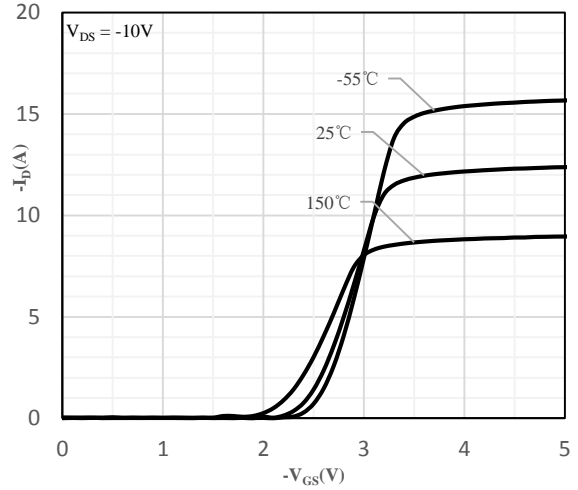


Fig 8 Transfer Characteristics

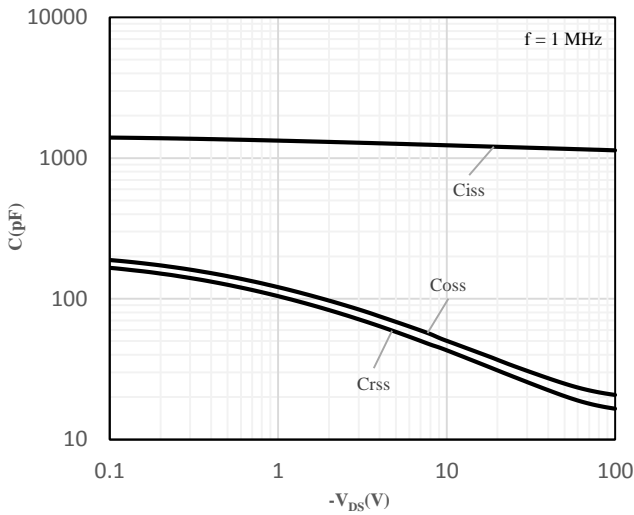


Fig 9 Capacitance Characteristics

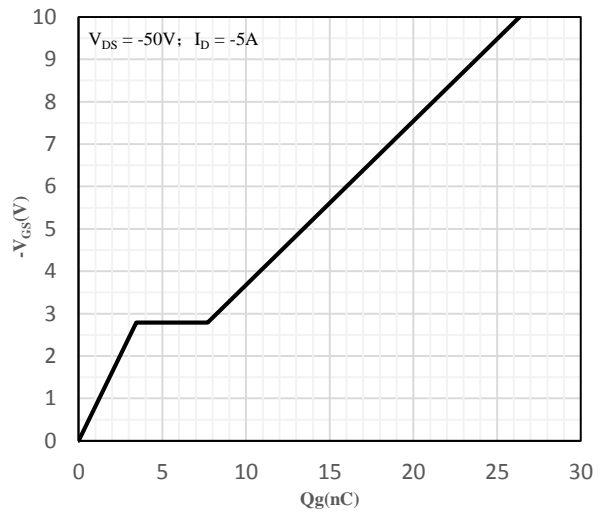


Fig 10 Gate-Charge Characteristics

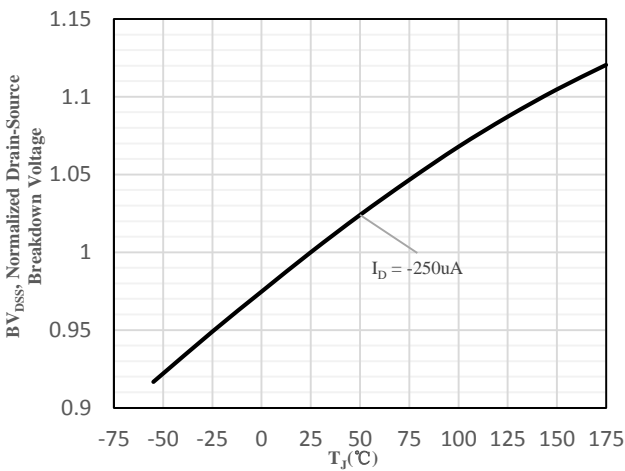


Fig 11 Normalized Breakdown Voltage vs. Junction Temperature

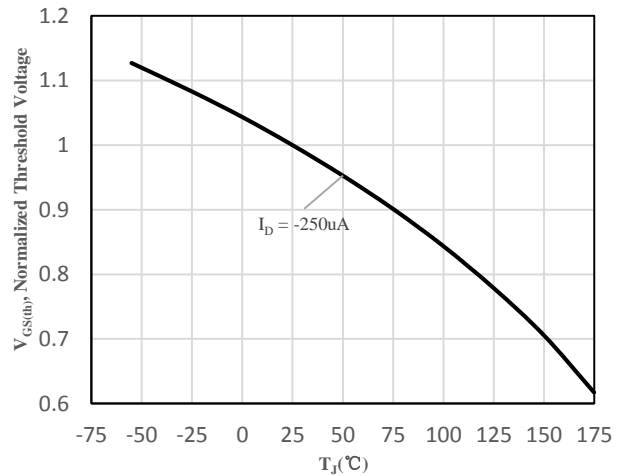
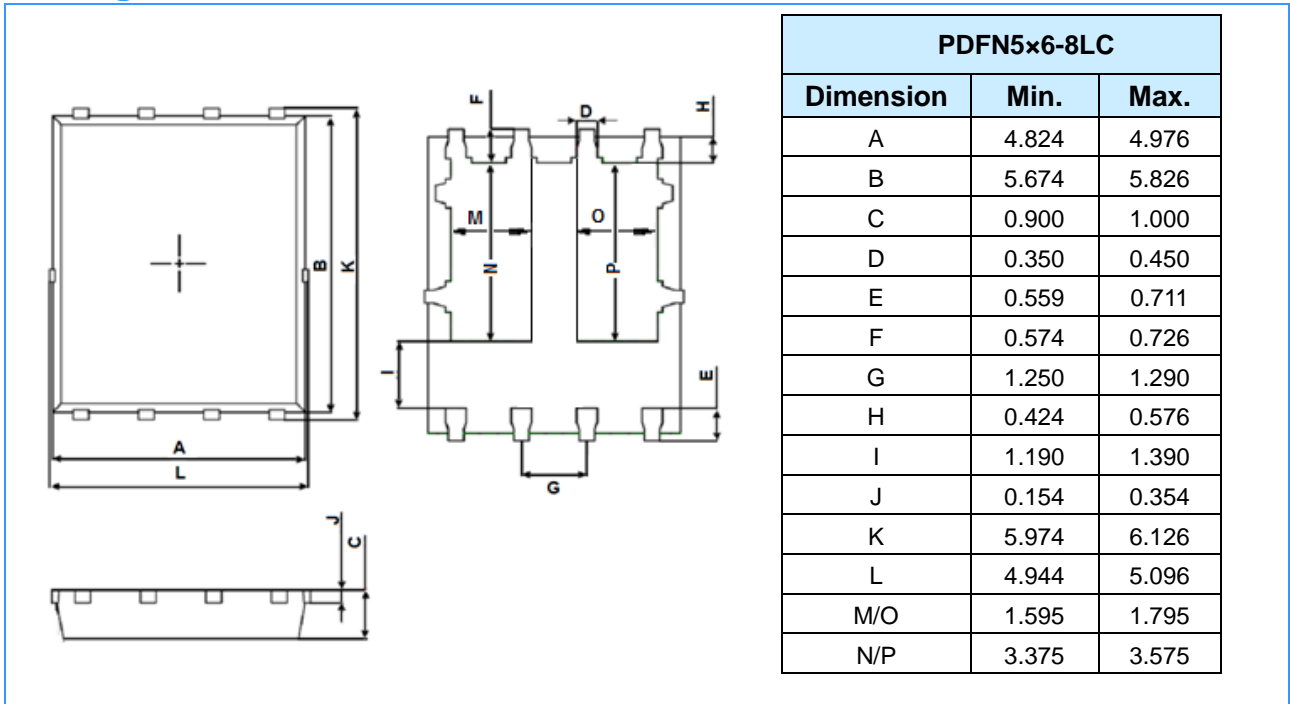


Fig 12 Normalized $V_{GS(th)}$ vs. Junction Temperature

Package Outline Dimensions (Unit: mm)



Mounting Pad Layout (Unit: mm)

